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RESIN SEALING/MOLDING APPARTUS FOR ELECTRONIC PARTS

ABSTRACT OF THE DISCLOSURE

A fixture (142) for fixing an annular upper air isolation member (120) which is provided around an outer side of an upper mold section (100) to an upper mounting plate (114) is released, thereby rotating the air isolation member (120) by a rotational member (140) and fixing the same by a rotational position regulating member (141). An upper chase unit (110) is exchanged through an upper opening (122) which is defined by the upper mounting plate (114) and the rotated air isolation member (120). A lower chase unit (210) is also exchanged in a similar manner. Due to this structure, a sealing mechanism for a resin sealing/molding apparatus for electronic parts which can readily and quickly exchange a mold in response to small lot production of various types of products is provided.

Fig 2A



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